

Figure 1. Block Diagram

Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description
1	XIN / CLKIN	I	Crystal connection or External reference clock input.
2	XOUT	0	Crystal connection. If using an external reference, this pin should be left open.
3	SSON	I	Spread Spectrum ON/OFF. Spread Spectrum function enabled when HIGH, disabled when LOW. Has an internal pull-up resistor.
4	GND	Р	Ground
5	ModOUT	0	Modulated clock output
6	MR	I	Modulation Rate Select. When LOW selects Low Modulation Rate. Selects High Modulation Rate when pulled HIGH. Has an internal pull-up resistor.
7	SSEXTR	I	Analog Deviation Selection through external resistor to GND.
8	V_{DD}	Р	3.3 V supply Voltage.

Table 2. OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{DD}	Supply Voltage	3	3.6	V
T _A	Operating Temperature	0	70	°C
C _L	Load Capacitance		10	pF
C _{IN}	Input Capacitance		7	pF

Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Rating	Unit
V_{DD}, V_{IN}	Voltage on any input pin with respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage temperature	-65 to +125	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Rating	Unit
TJ	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
VDD	Supply Voltage		3.0	3.3	3.6	V
V _{IL}	Input LOW Voltage				0.8	V
V _{IH}	Input HIGH Voltage		2.0			V
I _{IL}	Input LOW Current	V _{IN} = 0 V			25	μΑ
I _{IH}	Input HIGH Current	$V_{IN} = V_{DD}$			25	μΑ
V _{OL}	Output LOW Voltage	I _{OL} = 8 mA			0.4	V
V _{OH}	Output HIGH Voltage	I _{OH} = -8 mA	2.4			V
I _{CC}	Static Supply Current	XIN / CLKIN pulled low			50	μΑ
I _{DD}	Dynamic Supply Current	Unloaded Output			20	mA
Z _o	Output Impedance			30		Ω

Table 5. SWITCHING CHARACTERISTICS

Parameter	Test Conditions	Min	Тур	Max	Unit
Input Frequency* / ModOUT		15		50	MHz
Duty Cycle (Notes 1 and 2)	Measured at V _{DD} / 2	45	50	55	%
Output Rise Time (Notes 1 and 2)	Measured between 20% to 80%			1.8	ns
Output Fall Time (Notes 1 and 2)	Measured between 80% to 20%			1.6	ns
Cycle-to-Cycle Jitter (Note 2)	Unloaded output with SSEXTR OPEN @ 27 MHz		± 150	±250	ps
PLL Lock Time (Note 2)	Stable power supply, valid clock presented on XIN / CLKIN			3	ms

^{*}Functionality with Crystal is guaranteed by design and characterization. Not 100% tested in production.

^{1.} All parameters are specified with10 pF loaded outputs.

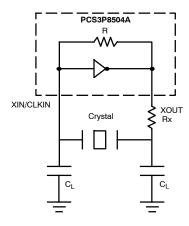
^{2.} Parameter is guaranteed by design and characterization. Not 100% tested in production.

TYPICAL CRYSTAL SPECIFICATIONS

FUNDAMENTAL AT CUT PARALLEL RESONANT CRYSTAL

Nominal frequency	27 MHz
Frequency tolerance	±50 ppm or better at 25°C
Operating temperature range	-25°C to +85°C
Storage temperature	-40°C to +85°C
Load capacitance (C _P)	18 pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

NOTE: C_L is the Load Capacitance and Rx is used to prevent oscillations at overtone frequency of the Fundamental frequency.



 $C_L = 2 * (C_P - C_S),$

Where C_P = Load capacitance of crystal from crystal vendor datasheet C_S = Stray capacitance due to C_{IN} , PCB, Trace etc.

Figure 2. Typical Crystal Interface Circuit

SWITCHING WAVEFORMS

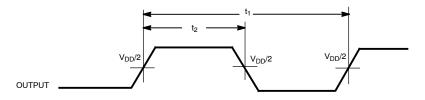


Figure 3. Duty Cycle Timing

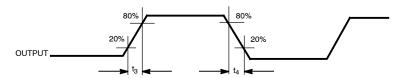
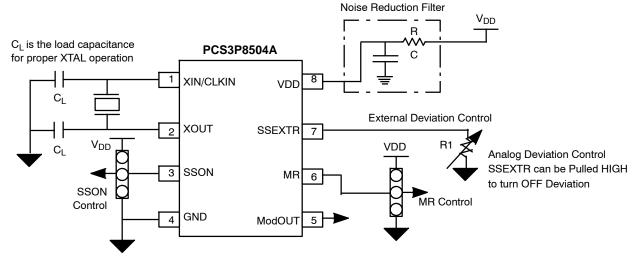


Figure 4. Output Rise/Fall Time



OTE: SSON (Pin#3) MR (Pin#6): Connect to V_{DD} or GND Refer to Pin Description table for Functionality details

Figure 5. Application Schematic

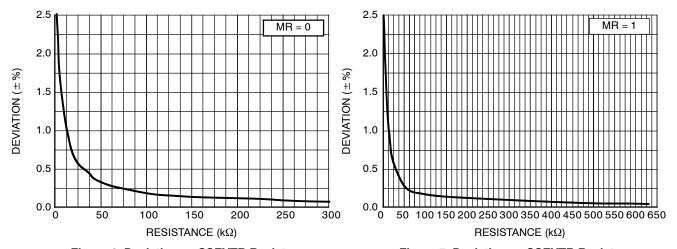


Figure 6. Deviation vs SSEXTR Resistance Chart at 27 MHz

Figure 7. Deviation vs SSEXTR Resistance Chart at 27 MHz

NOTE: Device to Device variation of Deviation is $\pm 10\%$

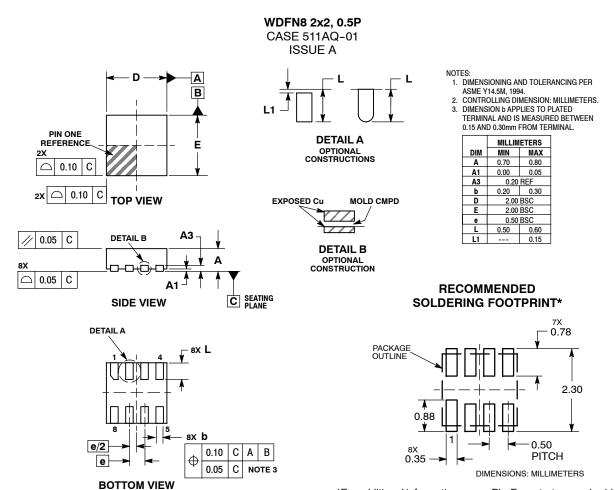
ORDERING INFORMATION

Part Number	Top Marking	Temperature	Package Type	Shipping [†]
PCS3P8504AG-08CR	DA	0°C to +70°C	8-Pin (2 mm x 2 mm) WDFN(TDFN) (Pb-Free)	Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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